Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	594	"257"/$.ccls. and mold with (protrus$4 project$4) and (chip die ic) and (substrate board carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:17
L2	343	"257"/$.ccls. and mold with (protrus$4 project$4) and (chip die ic) and (substrate board carrier) with (open$4 via hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:28
L3	134	"438"/$.ccls. and mold with (protrus$4 project$4) and (chip die ic) and (substrate board carrier) with (open$4 via hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:32
L4	57	"361"/$.ccls. and mold with (protrus$4 project$4) and (chip die ic) and (substrate board carrier) with (open$4 via hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:34
L5	78	"29"/$.ccls. and mold with (protrus$4 project$4) and (chip die ic) and (substrate board carrier) with (open$4 via hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:34